TEA1723FT

HV start-up flyback controller with integrated MOSFET for 11 W applications, 1750 Hz burst frequency

Rev. 2.1 — 7 June 2012 Product data sheet

1. Product profile

1.1 General description

The TEA1723 is a small and low cost module Switched Mode Power Supply (SMPS) controller IC for power applications (up to 11 W) and operates directly from the rectified universal mains input. The device includes a high voltage power switch (700 V) and has been optimized for flyback converter topologies to provide high-efficiency over the entire load range with ultra-low power consumption in the no-load condition. It provides a circuit for start-up directly from the rectified mains voltage without any external bleeder circuits.

The converter operates as a regulated voltage source from no-load up to the maximum output current and operates as current source that delivers the maximum current over a broad output voltage range. Using the TEA1723, a low power converter can be built at minimum cost and with the minimum number of external components.

The controller regulates the output voltage with primary-side sensing which eliminates the need for an additional secondary feedback circuitry and simplifies the design. At higher power levels, a frequency and current control mode is used. It operates with burst mode control at low power levels and no-load condition. The burst mode minimizes audible noise and provides an energy saver state which reduces the power consumption in no-load condition. The Burst mode frequency of 1750 Hz enables no-load power consumption < 53 mW at 230 V (AC) mains input.

1.2 Features and benefits

Power features:

- Low power SMPS controller with integrated power switch designed for applications up to 11 W
- 700 V high voltage power switch for global mains operation
- Primary sensing for control of the output voltage without optocoupler and secondary feedback circuitry
- Minimizes audible noise in all operation modes
- Energy Star 2.0 compliant
- Jitter function for reduced EMI

Green features:

- Enables no-load power consumption below < 53 mW
- Very low supply current in no-load condition with energy saver mode
- Incorporates a high voltage start-up circuit with zero current consumption under normal switching operation
- Available in halogen-free and Restriction of Hazardous Substances (RoHS) SO7 package

Protective functions:

- OverVoltage Protection (OVP) on Feedback control (FB) pin with auto-restart
- UnderVoltage LockOut (UVLO) protection on IC supply pin
- OverTemperature Protection (OTP)
- Soft-start by reduced peak current for zero and low output voltage
- Demagnetization protection for guaranteed discontinuous conduction mode operation
- Open and short-circuit protection of the Feedback control (FB) pin
- Short-circuit protection of the charger output

1.3 Applications

- Battery chargers for cellular phones, tablet pc and other power adapters up to 11 W
- Standby supply for TV, desktop PC and set-top boxes
- Power supply for white goods applications

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Power switch (Pin: DRAIN)						
R_{DSon}	drain-source on-state resistance	I_{ds} = 30 mA; T_j = 25 °C	3.5	4.8	6	Ω
Oscillator (Pins: DRAIN and SOURCE)						
f_{burst}	burst frequency	burst frequency in CVB mode, without jitter	1575	1750	1925	Hz
$f_{osc\text{-}high}$	oscillator frequency High	maximum switching frequency in CV and CC mode, without jitter	48	50.5	53	kHz
Supply (Pin: VCC)						
$V_{CC(startup)}$	start-up supply voltage		15	17	19	V
$V_{CC(stop)}$	stop supply voltage	undervoltage lockout of IC	7.5	8.5	9.5	V

2. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
TEA1723FT/N1	SO7	plastic small outline package; 7 leads; body width 3.9 mm	SOT1175-1

3. Block diagram

3.1 Block diagram

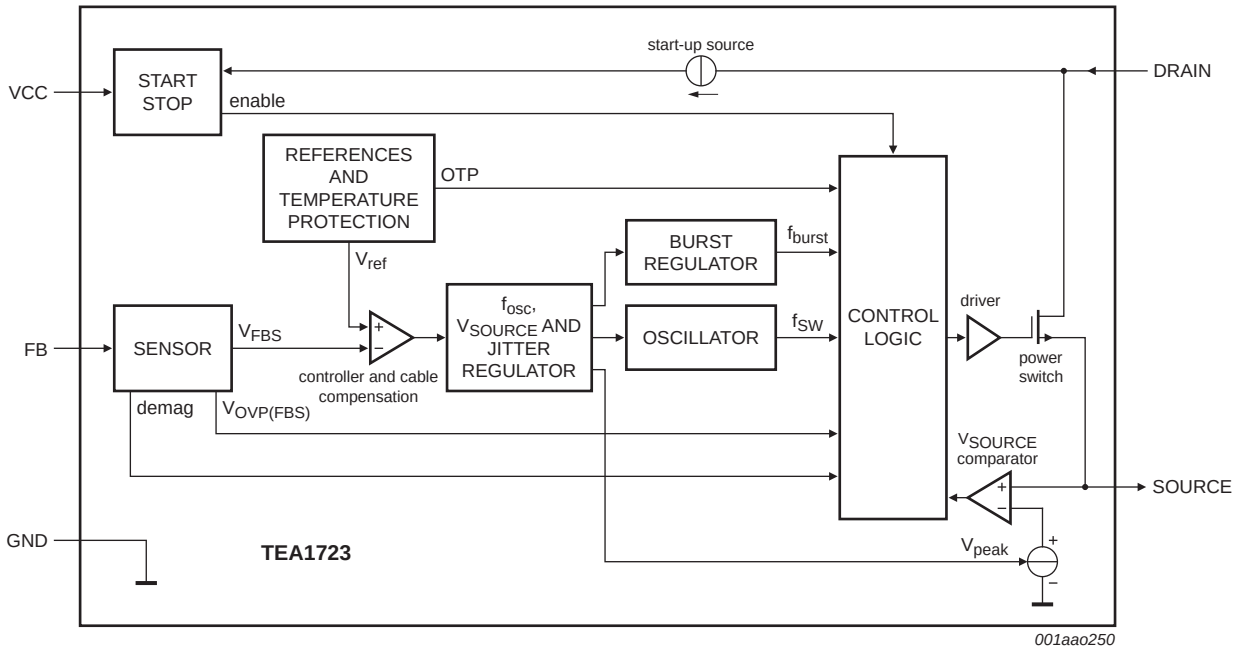


Fig 1. Block diagram

4. Pinning information

4.1 Pinning

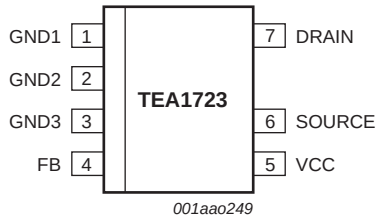


Fig 2. Pinning top view

4.2 Pin description

Pin	Pin name	I/O type	Pin description
1	GND1		ground
2	GND2		ground
3	GND3		ground
4	FB	I	feedback input for voltage sensing
5	VCC	I	supply input
6	SOURCE	O	source for power switch
7	DRAIN	I	drain of power switch
-	-		high voltage spacer

5. Functional description

5.1 Start-up

The TEA1723 starts up by charging the VCC capacitor until the $V_{CC(start)}$ level. The charging current flows from the high voltage DRAIN pin via an internal start-up current source to the VCC pin.

Once the start level has been reached the start-up current source is switched off. During switching operation, the start-up current source remains current-less and has zero bleeder loss.

5.2 Primary sensing

The FB input senses the reflected secondary voltage on the primary side. The FB input has a sample and hold function that samples the FB voltage on the secondary stroke to control the output voltage.

The sampled V_{FBS} voltage is the input for the TEA1723's control loop and defines the operating mode.

5.3 Operating modes

The TEA1723 operates in three modes, one of which is active at the time. The three modes in order of decreasing load impedance are:

- CVB: Constant Voltage with Burst mode
- CV: Constant Voltage mode
- CC: Constant Current mode

The converter acts as a voltage source in CVB and CV modes.

The converter acts as a current source in CC mode.

5.3.1 Constant Voltage with Burst mode (CVB)

At low power, the TEA1723 operates in Burst mode.

Burst mode operates with a V_{SOURCE} = 100 mV, a switching frequency of 22.5 kHz and burst duty-cycle regulation by sensing the FB voltage.

The TEA1723 features an energy save function that puts the main part of the analogue blocks in a sleep mode with low supply current in burst mode. The burst mode enables the energy save mode in the non-switching part of the burst. The IC switches to the nominal supply just before new burst starts.

Transition from burst mode to CV mode happens at 100 % burst duty cycle: a burst completely filled with 32 pulses. This 100 % pulse train is identical to the lowest power level of the CV mode. The TEA1723 changes directly from burst mode to CV mode if the FB voltage drops below 2.4 V in burst mode.

5.3.2 Constant Voltage mode (CV)

At higher power levels, the TEA1723 operates in CV mode. The output voltage is sensed by the FB pin and the control keeps the output voltage constant over the power range.

CV mode starts at 22.5 kHz switching frequency and I_{SOURCE} regulation at the V_{SOURCE} minimum level of 100 mV.

With an increasing power output, the V_{SOURCE} level and the switching frequency are also increased.

CV mode is exited when the maximum power level is reached. Maximum power occurs at I_{SOURCE} regulation at the V_{SOURCE} maximum level of 555 mV and a maximum switching frequency of 50.5 kHz.

5.3.3 Constant Current mode (CC)

The CC mode starts at maximum power delivery and keeps the output current constant for decreasing output voltage.

CC mode is enabled when the converter is operating at the maximum switching frequency, with the maximum primary peak current when the FB voltage drops below the regulated level.

CC mode operation controlled is by regulation of the switching frequency from 50.5 kHz down to 22.5 kHz and by I_{SOURCE} regulation from the maximum V_{SOURCE} level of 555 mV until level of V_{SOURCE} is 0.21 V. The V_{SOURCE} level of 0.21 V equals the level at start-up with zero output voltage and the output capacitor discharged or on a short-circuit of the charger output.

5.4 Jitter

The TEA1723 features a jitter function for ElectroMagnetic Interference (EMI) reduction. The switching frequency is 7 % typical for the spread spectrum. The sweep frequency is a low frequency of approximately 200 Hz. To keep the output power constant, the V_{SOURCE} level is jittered with the opposite polarity. The jitter is active in all operation modes except burst mode.

6. Limiting values

Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
T_{amb}	ambient temperature			-40	+85	°C
T_j	junction temperature			-40	+150	°C
T_{stg}	storage temperature			-55	+150	°C
V_{ESD}	electrostatic discharge voltage	CDM; all pins		-500	+500	V
		HBM; all pins, except pin 7	[1]	-2000	+2000	V
		HBM; pin 7	[1]	-1000	+1000	V
Voltages						
V_{DRAIN}	voltage on pin DRAIN			-2	+700	V
V_{SOURCE}	voltage on pin SOURCE			-0.3	+5	V
V_{CC}	voltage on pin VCC			-0.3	+35	V
V_{FB}	voltage on pin FB			-20	+5	V
Currents						
I_{DRAIN}	current on pin DRAIN			-0.1	+1.5	A
I_{SOURCE}	current on pin SOURCE			-1.5	+0.1	A

[1] Human body model: equivalent to discharging a 100 pF capacitor through a 1.5 kΩ series resistor.

7. Thermal characteristics

Table 4. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air; SO7 package; on open PCB of 2.2 cm X 2.2 cm; 2-layer; 70 µm Cu	-	136	-	K/W
		in free air; SO7 package; on open PCB of 3 cm X 6 cm; 1-layer; 35 µm Cu operating charger	-	136	-	K/W

8. Characteristics

Table 5. Characteristics

V_{CC} = 20 V; V_{FB} = 0 V; R_{source} = 0.75 Ω; $T_{j\text{-}switch}$ = 25 °C; $T_{j\text{-}controller}$ = 25 °C; all voltages referenced to GND, positive currents flow into the IC, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Supply (Pin: VCC)						
$I_{CC(startup)0V}$	start-up supply current	V_{CC} = 0 V	-1.6	-1.2	-0.8	mA
$I_{CC(startup)17V}$	start-up supply current	V_{CC} = $V_{CC(startup)}$	-1.6	-0.7	-0.2	mA
$I_{CC(energysave)}$	supply current in energy save	V_{FB} = 2.8 V, non-switching	90	130	170	µA
$I_{CC(50kHz)}$	supply current at 50 kHz	in CC mode	530	750	970	µA
$V_{CC(startup)}$	start-up supply voltage		15	17	19	V
$V_{CC(stop)}$	stop supply voltage	undervoltage lockout of IC	7.5	8.5	9.5	V
T_{otp}	overtemperature protection threshold temperature on controller die		-	150	-	°C
$T_{otp(hys)}$	overtemperature protection temperature hysteresis		-	50	-	°C
Feedback (Pin: FB)						
$V_{th(ovp)fbck}$	feedback overvoltage protection threshold voltage		3.1	3.2	3.3	V
$V_{ref(fbck)}$	feedback reference voltage	in CV ode	2.5	2.55	2.6	V
$V_{th(fbck)CV}$	constant voltage mode feedback threshold voltage	in burst mode operation	2.35	2.4	2.45	V
$V_{th(det)demag(fb)}$	demagnetization detection voltage level on FB pin		25	50	75	mV
Oscillator (Pins: DRAIN and SOURCE)						
f_{burst}	burst frequency	burst frequency in CVB mode, without jitter	1575	1750	1935	Hz
f_{jit}/f_{sw}	jitter frequency to switching frequency ratio	in all operation modes except in CVB mode	5	7	9	%
$f_{osc\text{-}high}$	oscillator frequency High	maximum switching frequency in CV and CC mode, without jitter	48	50.5	53	kHz
$f_{osc\text{-}low}$	oscillator frequency Low	minimum switching frequency in CV and CC mode, without jitter. Switching frequency in CVB mode	21	22.5	24	kHz
f_{sweep}	jitter sweep frequency		-	200	-	Hz
δ_{max}	maximum duty cycle		72	75	78	%

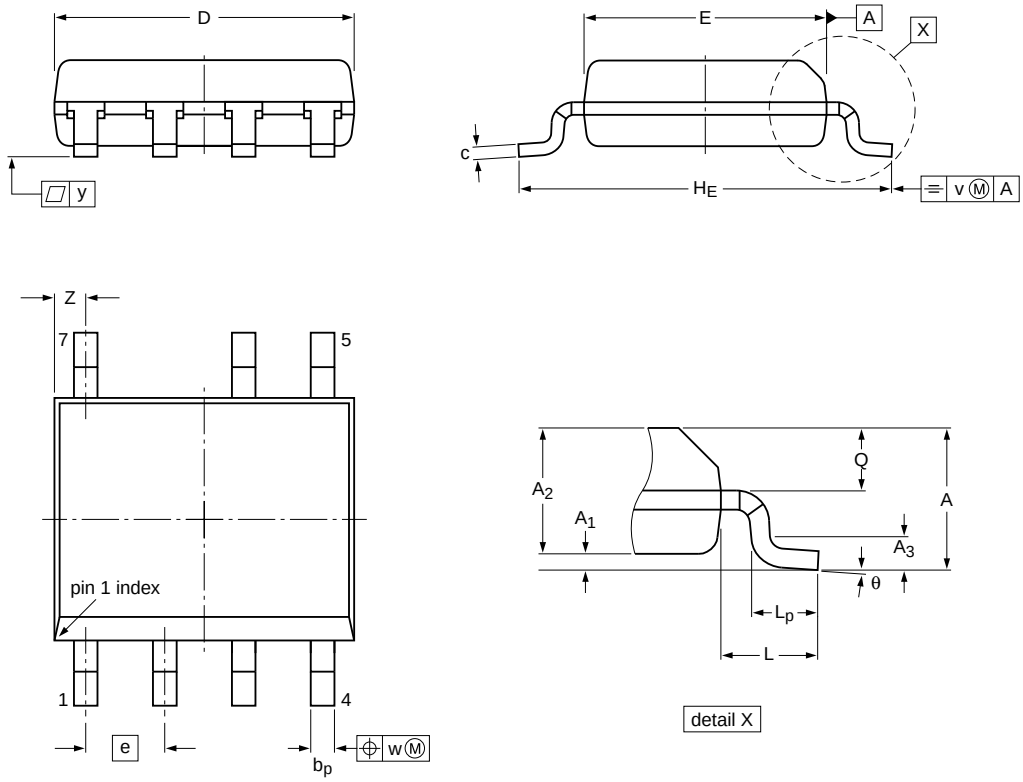
Table 5. Characteristics *…continued*

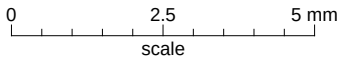
V_{CC} = 20 V; V_{FB} = 0 V; R_{source} = 0.75 Ω; $T_{j\text{-}switch}$ = 25 °C; $T_{j\text{-}controller}$ = 25 °C; all voltages referenced to GND, positive currents flow into the IC, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Power switch (Pin: DRAIN)						
$I_{drain(off)}$	off-state drain current	V_{DRAIN} = 325 V	-	1	-	µA
R_{DSon}	drain-source on-state resistance	T_j = 25 °C; I_{ds} = 30 mA	3.5	4.8	6	Ω
$V_{(BR)DS}$	drain-source breakdown voltage		700	-	-	V
Peak current comparator (Pin: SOURCE)						
t_{PD}	propagation delay time	dV/dt = 0.2 V/µs	-	100	-	ns
t_{leb}	leading edge blanking time		290	325	360	ns
$V_{ref\text{-}peak\text{-}high}$	reference voltage, high peak voltage	maximum peak voltage in CV and CC modes, without jitter	0.525	0.555	0.585	V
$V_{ref\text{-}peak\text{-}low}$	reference voltage, low peak voltage	in CVB mode	0.085	0.1	0.115	V
$V_{ref\text{-}0\ V}$	reference voltage at start-up or 0 V feedback voltage	in CC mode with V_{FBS} = 0 V	0.18	0.21	0.24	V

9. Package outline

SO7: plastic small outline package; 7 leads; body width 3.9 mm **SOT1175-1**





Dimensions

Unit		A	A_1	A_2	A_3	b_p	c	D	E	e	H_E	L	L_p	Q	v	w	y	Z	θ
	max	1.75	0.250	1.45		0.49	0.25	5.0	4.0		6.2		1.0	0.70				0.7	8°
mm	nom		0.175	1.35	0.25	0.40	0.20	4.9	3.9	1.27	6.0	1.05	0.7	0.67				0.5	4°
	min		0.100	1.25		0.36	0.19	4.8	3.8		5.8		0.4	0.60	0.25	0.25	0.1	0.3	0°

Note
1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

sot1175-1_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1175-1	- - -	- - -	- - -			~~10-03-30~~ 10-04-21

Fig 3. Package outline SOT1175-1 (SO7)

10. Revision history

Table 6. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
TEA1723FT v.2.1	20120607	Product data sheet	-	TEA1723FT v.2
Modifications:	• Symbol $t_{d(OCP)}$ changed to t_{PD} in table 5 on page 8. • Data sheet title changed.			
TEA1723FT v.2	20120508	Product data sheet	-	TEA1723FT v.1
TEA1723FT v.1	20120127	Preliminary data sheet	-	-

11. Legal information

11.1 Data sheet status

Document status[1] [2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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13. Contents

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